

Sensors and Materials

Special Issue on Advanced Methods and Devices for Remote Sensing

Call for Papers

Remote sensing is a non-contact way to obtain all kinds of data of the observed object, and earth observation is one of the most important application fields. The rise of new remote sensing platforms and technologies such as light field imaging, UAV remote sensing, and ground-based remote sensing has led to new applications of remote sensing technology, such as GeoAI, smart city and unmanned driving. Numerous studies have shown that new remote sensing methods and applications have promoted the development of industry and technology. This special issue focuses on new remote sensing devices, advanced data processing/analysis methods, new applications of remote sensing, and geospatial artificial intelligence (GeoAI) and big data in remote sensing.

Scope:

- New remote sensing devices
- Advanced data processing/analysis methods
- New applications of remote sensing
- GeoAI and big data in remote sensing

Submission due date: September 30, 2021

Publication date (planned): Second half of 2021

Journal website: <https://myukk.org/>

Guest Editor: Prof. Lei Deng and Prof. FuZhou Duan (Capital Normal University, Beijing)

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